



2814

Paper #15/C(18)
in wrong 11/1/01
case Hayes
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Trung T. Doan

Serial No.: 09/506,204

Filed: February 17, 2000

For: CONTACT/VIA FORCE FILL
TECHNIQUES AND RESULTING
STRUCTURES

Examiner: T. Quach


Group Art Unit: 2814

Attorney Docket No.: 3025.1US (95-1003.1)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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JoAnn Bawden
Typed/printed name of person whose signature is contained above

RESPONSE

Box Non Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

Responsive to the Office Action mailed July 31, 2001, Applicant responds to the Office Action as follows:

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity.

1. (Twice amended) A semiconductor device structure having a void-free, homogeneous aluminum alloy material within contact holes in an insulating layer, in direct contact with a

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